

Appl. No. 10/045,004  
Amendment dated: June 15, 2004  
Reply to OA of: March 23, 2004

This listing of claims will replace all prior versions and listings of claims in the application.

**Listing of Claims:**

1(currently amended). A lead-free solder consisting essentially of 7.0-10.0 wt% of Zn, ~~0.1-4.0~~ 0.25-0.5 wt% of Ag, 0.01-0.5 wt% of Al, 0.1-4.0 wt% of Ga, and the balance of Sn.

Claim 2(canceled).

3(original). The solder as claimed in Claim 1 further comprising 0.25-0.5 wt% of Ga.

4(original). The solder as claimed in Claim 1, which comprises 0.25-0.5 wt% of Ag.

Claim 5(canceled).

6(original). The solder as claimed in Claim 3, which comprises 0.25-0.5 wt% of Ag.

Claims 7-9(canceled).